

REMARKS/ARGUMENT

This Preliminary Amendment is being submitted to change the multiple dependent claims to single dependent claims in order to reduce the government filing fee.

EXPRESS MAIL CERTIFICATE

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail to Addressee (mail label # EL855846295US) in an envelope addressed to: Asst. Commissioner for Patents, Washington, D.C. 20231, on June 1, 2001:

Dorothy Jenkins


Name of Person Mailing Correspondence


Signature

June 1, 2001

Date of Signature

Respectfully submitted,


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APPENDIX B

VERSION WITH MARKINGS TO SHOW CHANGES MADE

37 C.F.R. § 1.121(b)(iii) AND (c)(ii)

CLAIMS:

3. A mounting structure of a semiconductor package as set forth in claim 1 [or 2], wherein a plating is provided on the surface of said pad and an inner surface of said via.

5. A mounting structure of a semiconductor package as set forth in claim 1 [or 2], wherein said via is projected from said pad in truncated cone shape to extend into a through hole of said printed circuit board and is integrally connected with said connection wiring.

APPENDIX A
"CLEAN" VERSION OF EACH PARAGRAPH/SECTION/CLAIM
37 C.F.R. § 1.121(b)(ii) AND (c)(i)

CLAIMS (with indication of amended or new):

Amended
35
(Amended) 3. A mounting structure of a semiconductor package as set forth in claim 1, wherein a plating is provided on the surface of said pad and an inner surface of said via.

Amended
37
(Amended) 5. A mounting structure of a semiconductor package as set forth in claim 1, wherein said via is projected from said pad in truncated cone shape to extend into a through hole of said printed circuit board and is integrally connected with said connection wiring.

New
39
(New) 8. A mounting structure of a semiconductor package as set forth in claim 2, wherein a plating is provided on the surface of said pad and an inner surface of said via.

(New) 9. A mounting structure of a semiconductor package as set forth in claim 2, wherein said via is projected from said pad in truncated cone shape to extend into a through hole of said printed circuit board and is integrally connected with said connection wiring.

(New) 10. A mounting structure of a semiconductor package as set forth in claim 8, wherein said via is projected from said pad in truncated cone shape to extend into a through hole of said printed circuit board and is integrally connected with said connection wiring.